IPC ASSOCIATION ELECTRONICS	© Copyright 2005.	Material Composition Declaration © Copyright 2005. IPC, Bannockburn, Illinois. All rights reserved under international and Pan-American copyright conventions.			nder both	This document is a declaration of the substances within the manufacturer listed item. Note: if the item is an assembly with lowel level parts, the declaration encompasses all lower level materials for which the manufacturer has engineering responsibility.									
1752-21.1		IPC Web Site for Information on IPC-1752 Standard Form Type http://www.ipc.org/IPC-175x Distribute			* Declaration Class * Class 6 - RoHS Yes/No, Homogeneous Materi				rials and M	als and Mfg Information					
Supplier	Information														
Company name*			Company unique ID			ı	Unique ID Authority				Respon	Response Date*			
onsemi										2024-05	2024-05-02				
Contact Name			Title - Contact]	Phone - Contact*				Email -	Email - Contact*			
Product-E	nv-Stewards		Product Enviro Compliance				NA				Produc	Product-Env-Stewards@onsemi.com			
Authorized Representative*			Title - Representative]	Phone - Representative*				Email -	Email - Representative*			
Product-Env-Stewards			Product Enviro Compliance				NA				Produc	Product-Env-Stewards@onsemi.com			
	Requester Item Number Mfr Item		Number Mfr Item Name			Effective Dat	te Versi	on 1	Manufacturing Site		Weight*	UOM	Unit Type		
		NVMFD5C466NLWF T6 40V LL S08FL T1G		DS		2024-05-02	2 MY1			89.49	mg	Each			
Manufac	turing Proccess Informa	ation													
7	Terminal Plating / Grid Array Material Terminal Base Alloy J-STD-			-STD-020 MS	L Rating	Peak Pro	ocess Body	/ Temperatu	re Max Time at Pea	k Tempera	ture Nur	nber of Reflow Cy	eles		
Matte Tin (Sn) - annealed CU Alloy			1			260		C	30	secoi	nds 3				
Comments															
evel 1 - ma	ximum time at peak temperat	ture during sol	dering is 10-3	0 seconds											
or more ir	nformation regarding materia	l composition	please refer to	page 3											

RoHS Material Composition Declaration			Declaration Type *	Detailed						
Directive 2015/863/EU amending RoHS Directive 2011/65/EU RoHS Definition: Quantity limit of 0.01% by mass (100 PPM) in homogeneous material for Cadmium and quantity limit of 0.1% by mass (1000 PPM) in homogeneous material for: Lead (Pb), Mercury (Hg), Hexavalent Chromium (Cr6+), Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE), and Bis(2-ethylhexyl) phthalate (DEHP), Benzyl-butyl phthalate (BBP), Dibutyl phthalate (DBP), Diisobutyl phthalate (DIBP).										
Please indicate whether any homogeneous material (as defined by the RoHS Directive, EU 2011/65/EU and implemented by the laws of the European Union member states) of the part identified on this form contains lead, mercury, cadmium, hexavalentchromium, polybrominated biphenyls and/or polybrominated diphenyl ethers (each a "RoHS restricted substance") in excess of the applicable quantity limit identified above. If a homogeneous material within the part contains a RoHS restricted substance inexcess of an applicable quantity limit, please indicate below which, if any, RoHS exemption you believe may apply. If the part is an assembly with lower level components, the declaration shall encompass all such components. Supplier certifies that it gathered the information it provides in this form using appropriate methods to ensure its accuracy and that such information is true and correct to the best of its keloardine shall encompass all such components. Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products with European Union member state laws that implement the RoHS Directive. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its paragraph. If the Company and the Supplier shall applier of that agreement, will be the sole and exclusivesource of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form. In the absence of such written agreement, the warranty rights and/or remedies of Supplier's Standard Terms and Conditions of Sale applicable to such part shall apply.										
RoHS Declaration * 4 - Item(s) does not contain RoHS restricted substance	s per the definition above except for selected exemp	tions Supplier Acceptance	* Accepted						
Exemption: 7a: Lead in high melting temperature type solders (i.e. lead based solder alloys containing 85% by weight or more lead).										
Exemption List Version	EL-2011/534/EU									
Declaration Signature										
Instructions: Complete all of the required fields on all pages of this form. Select the "Accepted" on the Supplier Acceptance drop-down. This will display the signature area. Digitally sign the declaration (if required by the Requester) and click on Submit Form to have the form returned to the Requester.										
Supplier Digital Signature Ra	astislav Drska	-En								

Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Substance Instructions: [A] select the Level (JIG A, JIG B, Requester or Supplier) [B] select the substance category (JIG or Requester) or enter a value (Supplier). [C] select the substance (JIG) or enter the substance and CAS (Other). [D] select a RoHS exemption, if applicable [E] enter the weight of the substance or the PPM concentration [F] Optionally enter the positive (+) and negative (-) tolerance in percent (Note: percent tolerance values are expected to cover a 3 sigma range of distribution unless otherwise noted).

Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Clip	0.34	mg	Supplier	Zinc (Zn)	7440-66-6		0.0004	mg
			Supplier	Iron (Fe)	7439-89-6		0.008	mg
			Supplier	Copper (Cu)	7440-50-8		0.3315	mg
			Supplier	Phosphorus (P)	7723-14-0		0.0001	mg
Die	0.36	mg	Supplier	Silicon (Si)	7440-21-3		0.36	mg
Die Attach Solder	0.82	mg	Supplier	Silver (Ag)	7440-22-4		0.0205	mg
			A	Lead (Pb)	7439-92-1	7a	0.7585	mg
			Supplier	Tin (Sn)	7440-31-5		0.041	mg
Lead Frame	37.39	mg	Supplier	Silver (Ag)	7440-22-4		0.3739	mg
			Supplier	Iron (Fe)	7439-89-6		0.0374	mg
			Supplier	Copper (Cu)	7440-50-8		36.9675	mg
			Supplier	Phosphorus (P)	7723-14-0		0.0112	mg
Mold Compound-Black	48.93	mg		Epoxy resin	proprietary data		3.6698	mg
			Supplier	Phenolic Resin	Proprietary Data		1.2233	mg
			Supplier	Silica Amorphous (SiO2)	7631-86-9		3.6698	mg
			Supplier	Carbon Black (C)	1333-86-4		0.2446	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		40.1226	mg
Plating	1.56	mg	Supplier	Tin (Sn)	7440-31-5		1.56	mg
Wire Bond - Cu	0.09	mg	Supplier	Copper (Cu)	7440-50-8		0.09	mg